Surface Mount Ultrafast Power Rectifiers

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- NRVUS and SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-O @ 0.125 in
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Rating:
 - Human Body Model (HBM) 3B (> 8 kV)
 - Machine Model (MM) C (> 400 V)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
Average Rectified Forward Current	I _{F(AV)}	3.0 @ T _L = 105°C	А
Non–Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	100	A
Operating Junction Temperature	TJ	- 65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



ON Semiconductor®

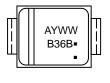
www.onsemi.com

ULTRAFAST RECTIFIERS 3 AMPERES 600 VOLTS



SMB CASE 403A

MARKING DIAGRAM



B36B	= Specific Device Code
А	= Assembly Location
Y	= Year
WW	= Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

[
Device	Package	Shipping [†]
MURS360BT3G	SMB (Pb-Free)	2,500 / Tape & Reel
NRVUS360VBT3G	SMB (Pb–Free)	2,500 / Tape & Reel
NRVUS360VDBT3G	SMB (Pb–Free)	2,500 / Tape & Reel
SURS8360BT3G	SMB (Pb–Free)	2,500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Semiconductor Components Industries, LLC, 2016 November, 2016 – Rev. 7

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ extsf{ heta}JL} \ R_{ hetaJA}$	14 125	°C/W

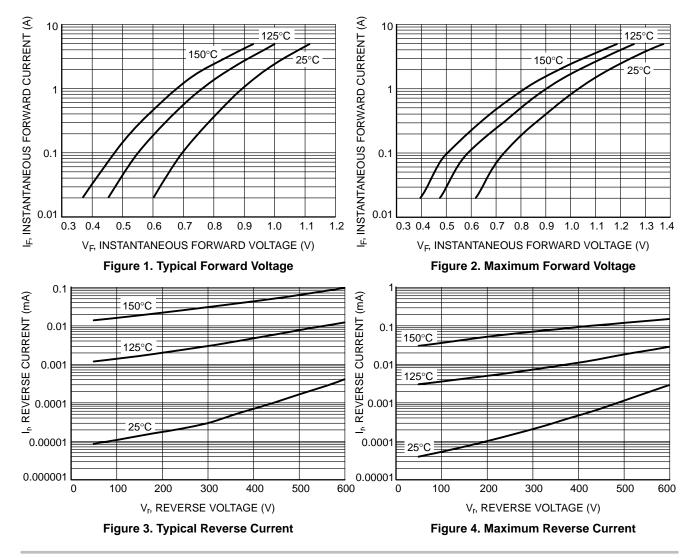
1. Mounted with minimum recommended pad size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

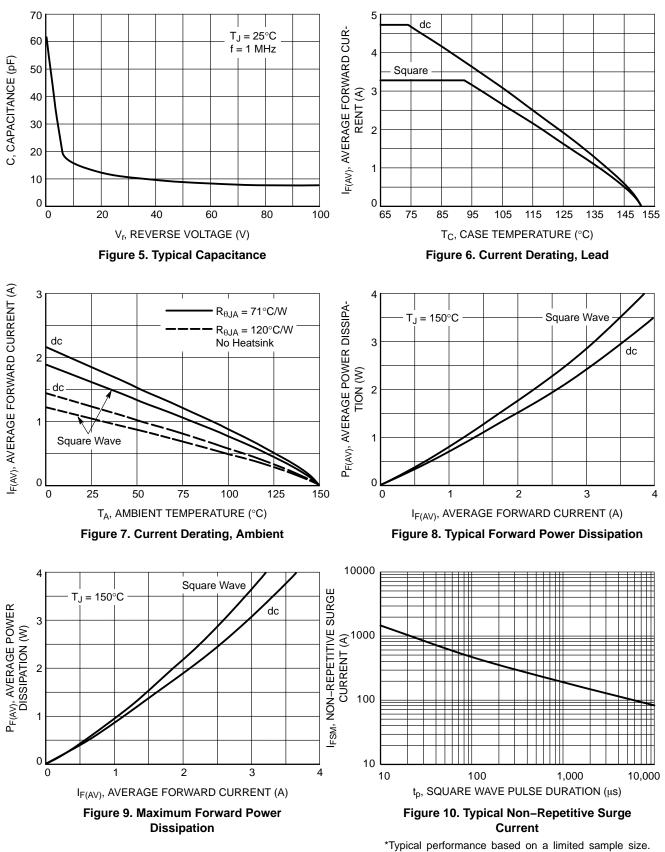
Characteristic	Symbol	Тур	Max	Unit V	
Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 3.0 \text{ A}, T_J = 25^{\circ}\text{C}$) ($i_F = 3.0 \text{ A}, T_J = 150^{\circ}\text{C}$)	VF	0.83	1.25 1.05		
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_J = 25^{\circ}C$) (Rated DC Voltage, $T_J = 150^{\circ}C$)	i _R	_ 95	3.0 150	μΑ	
Maximum Reverse Recovery Time ($i_F = 1.0 \text{ A}$, di/dt = 50 A/µs) ($i_F = 0.5 \text{ A}$, $i_R = 1.0 \text{ A}$, I_R to 0.25 A)	t _{rr}		75 50	ns	
Maximum Forward Recovery Time (i _F = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t _{fr}	_	50	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = $300 \,\mu$ s, Duty Cycle $\leq 2.0\%$.



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

^{*}Typical performance based on a limited sample size. ON Semiconductor does not guarantee ratings not listed in the Maximum Ratings table.

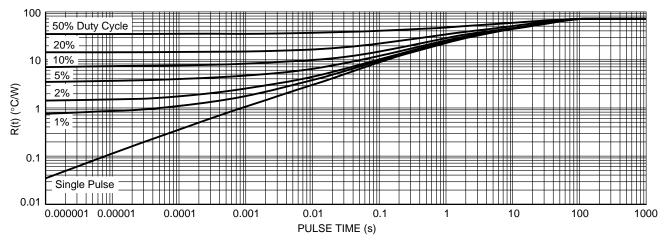
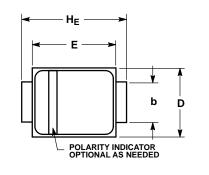
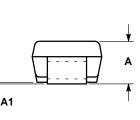


Figure 11. Thermal Response, Junction-to-Ambient

PACKAGE DIMENSIONS

SMB CASE 403A-03 **ISSUE J**



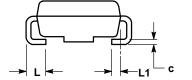


NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. 2.

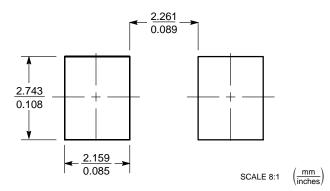
DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
q	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
Е	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
Г	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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